

ABSTRACT OF THE DISCLOSURE

A semiconductor device provided with a semiconductor chip having one surface bonded to a substrate, and the other surface bonded to a warp preventing sheet. Preferably, the warp preventing sheet has a coefficient of elasticity substantially equal to that of the substrate, or a coefficient of thermal expansion substantially equal to that of the substrate. Preferably, the base of the warp preventing sheet is made of material identical with that of the base of the substrate, and more preferably, the warp preventing sheet and the substrate are substantially equal in thickness to each other.

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